

EMIFIL® (Three-terminal capacitor)

DSS1NB3□□□□□□□□

Reference Specification

1. Scope

This reference specification applies to DSS1NB3 series.

2. Part Numbering

(Ex.)

DS	S	1	N	B3	2A	220	Q55	B
①	②	③	④	⑤	⑥	⑦	⑧	⑨

- ① Product ID (Disc-Type EMIFIL®)
- ② Structure S : Built-in Ferrite Beads Type
- ③ Style
- ④ Features
- ⑤ Temperature Characteristics B3: ±10% (-40~+85°C at 20°C)
- ⑥ Rated Voltage 2A :2A→100VDC, 1H→50VDC
- ⑦ Capacitance

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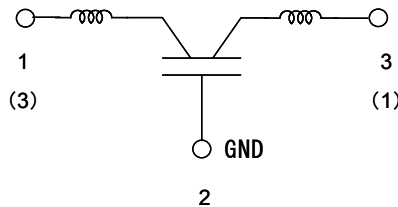
↓
Marked three digits system.(Ex. 22pF→220、22nF→223)

- ⑧ Lead Type
Q55 : Bulk
Lead Type :Straight Lead
Lead Length(l) 25.0 mm min. ※See item 9.

Q91 : Taping
Lead Type :Straight Lead
Dimension H: 20.0±1.0 mm ※See item 9.
- ⑨ Packaging Code A : Ammo Pack / B : Bulk / J:Reel

3. Rating

Operating temperature : -40 to +85°C
 Storage Temperature : -40 to +85°C
 Insulation Resistance : 50MΩ min.
 Rated Current : 6A(DC)
 Equivalent Circuit :



Others : See Table 1


Table 1

Customer Part Number	Murata Part Number	Capacitance	Temperature Characteristics	Rated Voltage	Withstanding Voltage	Unit Mass (Typical value)
	DSS1NB32A220Q55B	22 pF ± 10%	± 10%	100VDC	250VDC	0.45g
	DSS1NB32A220Q91A					
	DSS1NB32A220Q91J					
	DSS1NB32A330Q55B	33 pF ± 10%				
	DSS1NB32A330Q91A					
	DSS1NB32A330Q91J					
	DSS1NB32A470Q55B	47 pF ± 10%				
	DSS1NB32A470Q91A					
	DSS1NB32A470Q91J					
	DSS1NB32A680Q55B	68 pF ± 10%				
	DSS1NB32A680Q91A					
	DSS1NB32A680Q91J					
	DSS1NB32A101Q55B	100 pF ± 10%				
	DSS1NB32A101Q91A					
	DSS1NB32A101Q91J					

Customer Part Number	Murata Part Number	Capacitance	Temperature Characteristics	Rated Voltage	Withstanding Voltage	Unit Mass (Typical value)
	DSS1NB32A121Q55B	120 pF ± 10%	± 10%	100VDC	250VDC	0.45g
	DSS1NB32A121Q91A					
	DSS1NB32A121Q91J					
	DSS1NB32A151Q55B	150 pF ± 10%				
	DSS1NB32A151Q91A					
	DSS1NB32A151Q91J					
	DSS1NB32A221Q55B	220 pF ± 10%				
	DSS1NB32A221Q91A					
	DSS1NB32A221Q91J					
	DSS1NB32A271Q55B	270 pF ± 10%				
	DSS1NB32A271Q91A					
	DSS1NB32A271Q91J					
	DSS1NB32A331Q55B	330 pF ± 10%				
	DSS1NB32A331Q91A					
	DSS1NB32A331Q91J					
	DSS1NB32A471Q55B	470 pF ± 10%				
	DSS1NB32A471Q91A					
	DSS1NB32A471Q91J					
	DSS1NB32A681Q55B	680 pF ± 10%				
	DSS1NB32A681Q91A					
	DSS1NB32A681Q91J					
	DSS1NB32A102Q55B	1.0 nF ± 10%				
	DSS1NB32A102Q91A					
	DSS1NB32A102Q91J					
	DSS1NB32A152Q55B	1.5 nF ± 10%				
	DSS1NB32A152Q91A					
	DSS1NB32A152Q91J					
	DSS1NB32A222Q55B	2.2 nF ± 10%				
	DSS1NB32A222Q91A					
	DSS1NB32A222Q91J					
	DSS1NB32A332Q55B	3.3 nF ± 10%				
	DSS1NB32A332Q91A					
	DSS1NB32A332Q91J					
	DSS1NB32A472Q55B	4.7 nF ± 10%				
	DSS1NB32A472Q91A					
	DSS1NB32A472Q91J					
	DSS1NB32A682Q55B	6.8 nF ± 10%				
	DSS1NB32A682Q91A					
	DSS1NB32A682Q91J					
	DSS1NB32A103Q55B	10 nF ± 10%				
	DSS1NB32A103Q91A					
	DSS1NB32A103Q91J					
	DSS1NB32A153Q55B	15 nF ± 10%				
	DSS1NB32A153Q91A					
	DSS1NB32A153Q91J					
	DSS1NB32A223Q55B	22 nF ± 10%				
	DSS1NB32A223Q91A					
	DSS1NB32A223Q91J					
	DSS1NB31H333Q55B	33 nF ± 10%	± 10%	50VDC	125VDC	0.45g
	DSS1NB31H333Q91A					
	DSS1NB31H333Q91J					
	DSS1NB31H473Q55B	47 nF ± 10%				
	DSS1NB31H473Q91A					
	DSS1NB31H473Q91J					
	DSS1NB31H104Q55B	100 nF ± 10%				
	DSS1NB31H104Q91A					
	DSS1NB31H104Q91J					

4. Style and Dimension

See item 9.

5. MarkingTrade Mark : Marked as 

Capacitance : Marked three digits system. (Ex.221)

Rated Voltage : Marked voltage value.(100V)

6. Testing Conditions

<Unless otherwise specified>

Temperature : Ordinary Temperature 15 to 35°C

Humidity : Ordinary Humidity 25 to 85 %(RH)

<In case of doubt>

Temperature : 20 ± 2°C

Humidity : 60 to 70 %(RH)

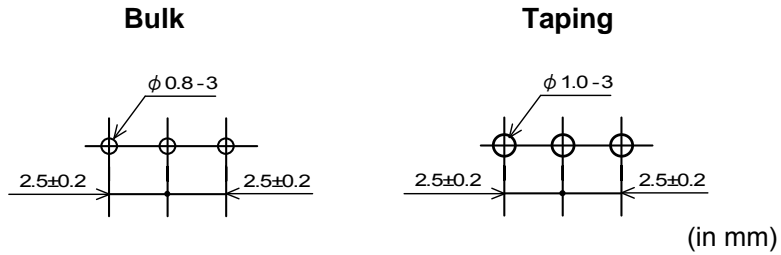
Atmospheric Pressure : 86 to 106 kPa

7. Performance

No.	Item	Specification	Test Method												
7.1	Appearance and Dimensions	Meet item 9.	Visual Inspection and measured with Slide Calipers.												
7.2	Marking	Marking is able to be read easily.	Visual Inspection.												
7.3	Capacitance and Tolerance	Meet item 3.	Table 2 <table border="1"> <thead> <tr> <th>Frequency</th> <th>Test Voltage</th> <th>Capacitance</th> </tr> </thead> <tbody> <tr> <td>1±0.1MHz</td> <td>1±0.2Vrms</td> <td>22pF~150pF</td> </tr> <tr> <td>1±0.1kHz</td> <td>1±0.2Vrms</td> <td>220pF~100nF</td> </tr> </tbody> </table>	Frequency	Test Voltage	Capacitance	1±0.1MHz	1±0.2Vrms	22pF~150pF	1±0.1kHz	1±0.2Vrms	220pF~100nF			
Frequency	Test Voltage	Capacitance													
1±0.1MHz	1±0.2Vrms	22pF~150pF													
1±0.1kHz	1±0.2Vrms	220pF~100nF													
7.4	Insulation Resistance(I.R.)	Meet item 3.	Test Voltage : Rated Voltage Time : 1 minute through a suitable resistor 1MΩ.												
7.5	Withstanding Voltage	Products shall not be damaged.	Test Voltage : 2.5 times for Rated Voltage Time : 1 to 5 seconds Charge Current : 10 mA max. It shall be applied between input / output terminal and ground terminal.												
7.6	Temperature Characteristics	Meet item 3.	Capacitance shall be measured at each step specified in Table 3 after reaching the thermal equilibrium. The capacitance change against the capacitance at step 3 shall be calculated. Table3 <table border="1"> <thead> <tr> <th>Step</th> <th>1</th> <th>2</th> <th>3</th> <th>4</th> <th>5</th> </tr> </thead> <tbody> <tr> <td>Temp. (°C)</td> <td>+20±2</td> <td>40±2</td> <td>+20±2</td> <td>+85±2</td> <td>+20±2</td> </tr> </tbody> </table>	Step	1	2	3	4	5	Temp. (°C)	+20±2	40±2	+20±2	+85±2	+20±2
Step	1	2	3	4	5										
Temp. (°C)	+20±2	40±2	+20±2	+85±2	+20±2										
7.7	Solderability	Along the circumference of terminal shall be covered with new solder at least 75%.	Flux : Ethanol solution of rosin,25(wt)% (dipped for 5 to 10 seconds) Pre-heat : 150±10°C, 60~90 s Solder : Sn-3.0Ag-0.5Cu Solder Temperature 245±5°C Immersion Time : 2 ± 0.5 seconds Immersion Depth : 2 to 2.5 mm from the bottom of the body.												
7.8	Resistance to Soldering Heat①	Meet Table 4. Table 4 <table border="1"> <tbody> <tr> <td>Appearance</td> <td>No damaged.</td> </tr> <tr> <td>Capacitance Change</td> <td>within ± 30%</td> </tr> <tr> <td>Withstanding Voltage</td> <td>No damaged.</td> </tr> </tbody> </table>	Appearance	No damaged.	Capacitance Change	within ± 30%	Withstanding Voltage	No damaged.	Flux : Ethanol solution of rosin,25(wt)% (dipped for 5 to 10 seconds) Pre-heat : 150±10°C, 60~90 s Solder : Sn-3.0Ag-0.5Cu Solder Temperature : 270 ± 5 °C Immersion Time : 3± 0.5 seconds Immersion Depth : 1.6 ± 0.7 mm from the bottom of the body. Then measured after exposure in the room condition for 4 to 24hours.						
Appearance	No damaged.														
Capacitance Change	within ± 30%														
Withstanding Voltage	No damaged.														
	Resistance to Soldering Heat②		Soldering iron output: 30W Tip temperature : 370±10°C Soldering time : 5s(+0/-1s)												

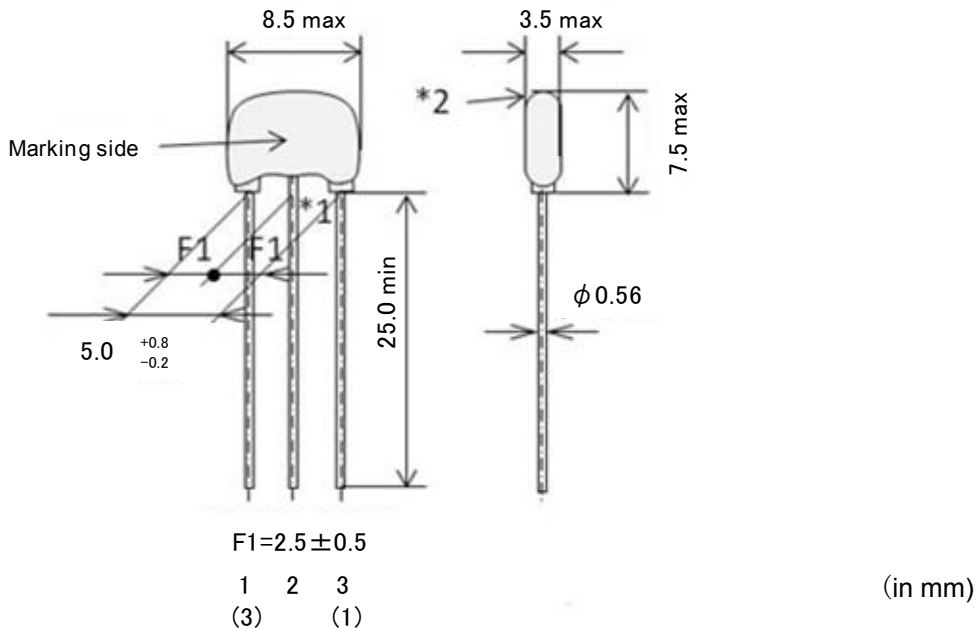
No.	Item	Specification	Test Method						
7.9	Humidity	Meet Table 5. Table 5	Temperature : 60°C Humidity : 90 to 95 %(RH) Time : 500 hours(+24-0 hours) Then measured after exposure in the room condition for 4 to 24hours.						
		<table border="1"> <tr> <td>Appearance</td> <td>No damaged.</td> </tr> <tr> <td>Capacitance Change</td> <td>within ± 30%</td> </tr> <tr> <td>Insulation Resistance</td> <td>10MΩ min.</td> </tr> </table>	Appearance	No damaged.	Capacitance Change	within ± 30%	Insulation Resistance	10MΩ min.	
Appearance	No damaged.								
Capacitance Change	within ± 30%								
Insulation Resistance	10MΩ min.								
7.10	Humidity Life		Temperature : 40 ± 2°C Humidity : 90 to 95 %(RH) Time : 500 hours(+24-0 hours) Applying Voltage : 1H/ Rated Voltage 50VDC 2A/ Rated Voltage 100VDC Then measured after exposure in the room condition for 4 to 24hours.						
7.11	Heat Life		Temperature : 85 ± 3°C Applying Voltage : 1H/ Rated Voltage 50VDC 2A/ Rated Voltage 100VDC Time : 500 hours(+24-0 hours) Then measured after exposure in the room condition for 4 to 24hours.						

8. Mounting Hole



9. Style and Dimension

9.1 Bulk(Straight Lead Type) : Q55B

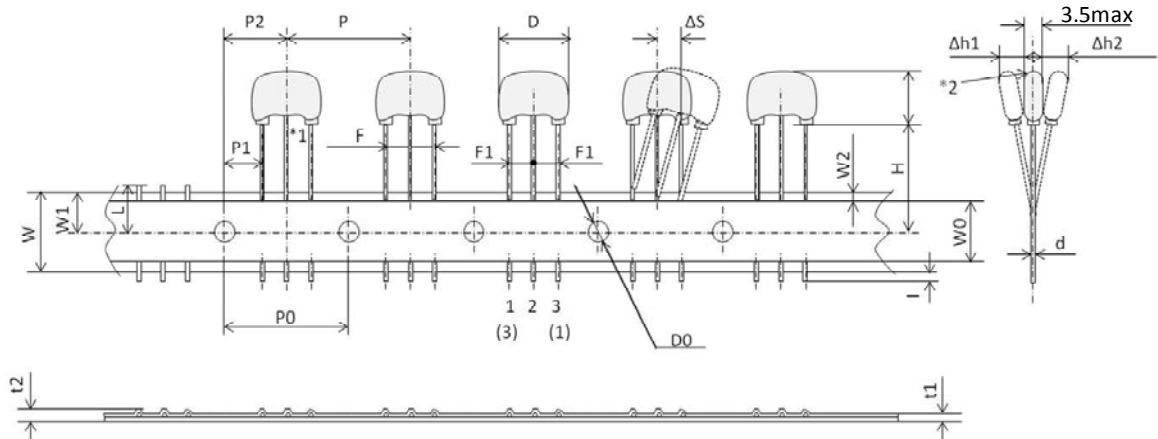


*1. Bottom of dielectric may be exposed.

*2. There should not be the exposure of the ferrite bead if a hole is on the top of ferrite bead.

9.2 Taping(Straight Lead Type) : Q91A or J

(All symbols in the illustrations below are described in Table 4)



- *1. Bottom of dielectric may be exposed.
- *2. There should not be the exposure of the ferrite bead if a hole is on the top of ferrite bead.

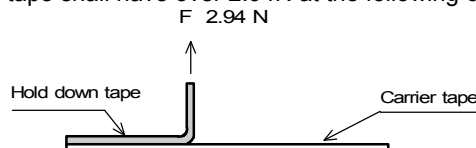
Table 4

Code	Description	Dimensions	Remark
P	Pitch of Component	12.7	Product Inclination ΔS Determines Crossing
P0	Pitch of Sprocket Hole	12.7±0.2	
P1	Length from Hole Center to Lead	3.85±0.7	
P2	Length from Hole Center to Component Center	6.35±1.3	
D	Width of Body	8.0 max.	
ΔS	Deviation along tape, Left or Right	0±1.0	
W	Carrier Tape Width	18.0±0.5	
W1	Position of Sprocket Hole	9.0 +0,-0.5	Tape Widthwise Shift
l	Protrusion Length	+0.5 ~ -1.0	
D0	Diameter of Sprocket Hole	φ 4.0±0.1	
d	Lead Diameter	φ 0.6	
t1	Total Tape Thickness	0.7±0.2	Includes Thickness of Bonding Tape
t2	Total Thickness, Tape and Lead Wire	1.5 max.	
Δh1	Deviation across Tape, front	1.0 max.	
Δh2	Deviation across Tape, rear	1.0 max.	
L	Portion to Cut in Case of Defect	11.0 +0,-1.0	
W0	Hold Down Tape Width	12.0±0.5	
W2	Hold Down Tape Position	1.5±1.5	
H	Lead length between sprocket hole and forming position	20.0±1.0	
F	Lead Spacing	5.0 +0.8,-0.2	
F1		2.5 +0.4,-0.2	

(in mm)

10. Taping

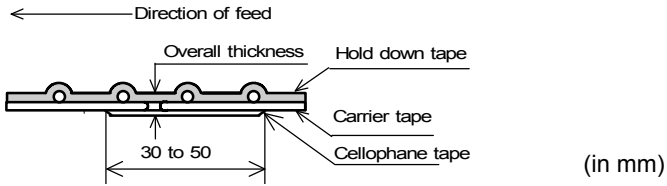
- (1) A maximum of 0.3% of the components quantity per reel or Ammo pack may be missing without consecutive missing components.
- (2) The adhesive power of the tape shall have over 2.94N at the following condition.



(3) Splicing method of tape

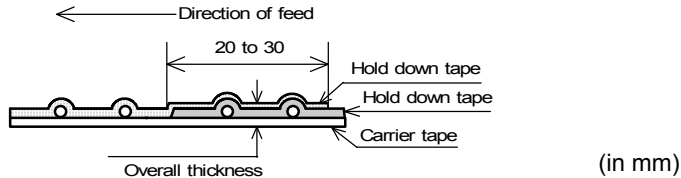
1. Carrier tape

Carrier tape shall be spliced by cellophane tape.
Overall thickness shall be less than 1.05 mm.



2. Hold down tape

Hold down tape shall be spliced with overlapping.
Overall thickness shall be less than 1.05 mm.



3. Both carrier tape and hold down tape

Both tapes shall be cut zigzag and spliced with splicing tape.

11. Packing

11.1 Packing quantity

The standard packing quantity is as follows.

(The packing quantity may be changed due to a fraction of order.)

Minimum Packing Form and Quantity

Terminal Configuration	A Unit Quantity	Packing Form	* Standard Quantity in a container (corrugated cardboard box)
Bulk	250 pcs.	In a plastic bag	5000pcs.
Taping	1500 pcs.	In an Ammo pack	7500pcs.
Taping	1500 pcs.	In a reel	6000pcs.

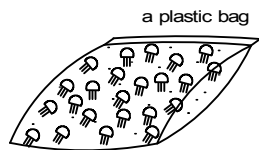
* A quantity in a container is depending on a quantity of an order.

11.2 Packing Form

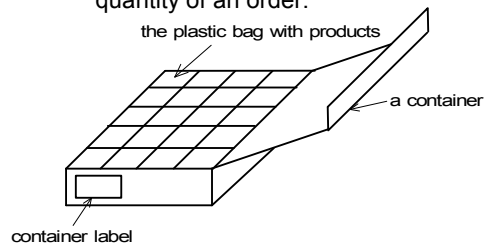
(1) Bulk

<A plastic bag pack>

1. Products are packed into a plastic bag.



2. The plastic bags are put into a container (corrugated cardboard box) depending on a quantity of an order.



13. Caution

13.1 Mounting holes

Mounting holes should be designed as specified in this specifications.
 Or different design from this specifications may cause cracks in ceramics which may lead to smoking / firing.

13.2 Caution for the product angle adjust work

Take care not to apply any mechanical stress to product body at the lead terminal bending process for product angle adjustment after insertion.

13.3 Limitation of Applications

Please contact us before using our products for the applications listed below which require especially high reliability for the prevention of defects which might directly cause damage to the third party's life, body or property.

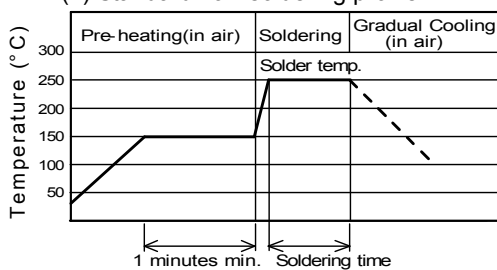
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|--|--|
| (1) Aircraft equipment | (7) Traffic signal equipment |
| (2) Aerospace equipment | (7) Disaster prevention / crime prevention equipment |
| (3) Undersea equipment | (9) Data-processing equipment |
| (4) Power plant control equipment | (10) Applications of similar complexity and /or reliability requirements to the applications listed in the above |
| (5) Medical equipment | |
| (6) Transportation equipment (vehicles, trains, ships, etc.) | |

14. Notice

14.1 Soldering

- (1) Use rosin-based flux. Do not use strong acidic flux with halide content exceeding 0.2(wt)% (chlorine conversion value).
 Use Sn-3.0Ag-0.5Cu solder

- (2) Standard flow soldering profile.



Solder temperature	Soldering time
250~260 °C	4~6s

- (3) Resistance to soldering iron goes in the following condition that tip temperature is 350 °C max. And soldering time is 5 s max.
- (4) Products and the leads should not be subjected to any mechanical stress during soldering process. (and also while subjected to the equivalent high temperature.)

14.2 Cleaning

Products shall be cleaned on following conditions.

- (1) Cleaning Temperature: 60°C max.(40°C max. for Isopropyl alcohol).
- (2) Ultrasonic cleaning shall comply with the following conditions, avoiding the resonance phenomenon at the mounted products and P.C.B.
 - Power : 20W / l max.
 - Frequency : 28kHz ~ 40kHz
 - Time : 5 minutes max.
- (3) Cleaning agent
 1. alcohol cleaning agents.
 - Isopropyl alcohol (IPA)
 2. Aqueous cleaning agent
 - Pine Alpha ST-100S
- (4) Ensure that residual flux and residual cleaning agent is completely removed.

Products should be thoroughly dried after aqueous agent has been removed with de-ionized water.
- (5) For other cleaning methods, please contact Murata engineering.

14.3 Operating Environment

- (1) Do not use products in corrosive gases such as chlorine gas, acid or sulfide gas.
- (2) Do not use products in the environment where water, oil or organic solvents may adhere to products.
- (3) Do not adhere any resin to products, coat nor mold products with any resin (including adhesive)to prevent mechanical and chemical stress on products.

14.4 Storage and handling requirements.

- (1) Storage period

Use the products within 12 months after delivered.
Solderability should be checked if this period is exceeded.
- (2) Storage environment condition

To prevent products quality deterioration, stored conditions should be controlled as follows ;

 1. Temperature : -10 to 40 degrees centigrade
 2. Humidity : 15 to 85% relative humidity
 3. Products should be stored without sudden changes in temperature and humidity.
Don't keep products in corrosive gases such as sulfur, chlorine gas or acid,
or it may cause oxidization of lead terminals resulting in poor solderability.
 4. Products should be stored on the palette for the prevention of the influence from humidity, dust and so on.
 5. Products should be stored in the warehouse without heat shock, vibration, direct sunlight and so on.
- (3) Handling Conditions

Care should be taken when transporting or handling product to avoid excessive vibration or mechanical shock.

15.  Note

- (1) Please make sure that your product has been evaluated in view of your specifications with our product being mounted to your product.
- (2) You are requested not to use our product deviating from the reference specifications.
- (3) The contents of this reference specification are subject to change without advance notice. Please approve our product specifications or transact the approval sheet for product specifications before ordering.

Murata:

<u>DSS1NB32A152Q91A</u>	<u>DSS1NB32A101Q91A</u>	<u>DSS1NB31H473Q91A</u>	<u>DSS1NB32A680Q91A</u>	<u>DSS1NB32A332Q91A</u>
<u>DSS1NB32A271Q91A</u>	<u>DSS1NB32A682Q91A</u>	<u>DSS1NB31H104Q91A</u>	<u>DSS1NB32A470Q91A</u>	<u>DSS1NB32A151Q91A</u>
<u>DSS1NB32A102Q91A</u>	<u>DSS1NB32A472Q91A</u>	<u>DSS1NB32A330Q91A</u>	<u>DSS1NB32A223Q91A</u>	<u>DSS1NB32A103Q91A</u>
<u>DSS1NB32A153Q91A</u>	<u>DSS1NB31H333Q91A</u>	<u>DSS1NB32A222Q91A</u>	<u>DSS1NB32A220Q91A</u>	<u>DSS1NB32A121Q91A</u>
<u>DSS1NB32A331Q91A</u>	<u>DSS1NB32A681Q91A</u>	<u>DSS1NB32A471Q91A</u>	<u>DSS1NB32A221Q91A</u>	